

# GCSP-20LD

## Low Density Silicone Thermal Interface Pad

### Features

- Low density, ideal for weight limited applications
- 2.0 W/m K thermal conductivity
- With single side adhesive
- Long term stability
- >10 kV breakdown voltage
- ROHS/REACH compliant



### Typical Applications

- Electric vehicle battery cooling
- Portable electronic devices
- RF circuits

### Configurations

Part number	Total thickness
GCSP-20LD-150x150-0.5	0.5mm
GCSP-20LD-150x150-3.0	3.0mm
GCSP-20LD-150x150-5.0	5.0mm

### Properties

Characteristic	Test Method	Value
Colour	Visual	Pink/White
Available thickness range (mm)	ASTM D374	0.3~5.0
Reinforcement Layer	-	Fibreglass
Thermal conductivity W/mK	ASTM D5470	2.0
Thermal impedance (°C-in <sup>2</sup> /W) @1.0mm 20PSI	ASTM D5470	0.6
Thermal impedance (°C-in <sup>2</sup> /W) @1.0mm 50PSI	ASTM D5470	0.48
Density g/cm <sup>3</sup>	ASTM D792	1.9
Hardness (Shore 00)	ASTM D2240	50
Dielectric breakdown strength, kV/mm	ASTM D149	>10.0
Tensile strength (PSI)	ASTM D149	>300
Operational temperature °C	EN344	-60 ~ +150
Volume resistivity (Ωcm)	ASTM D257	>10 <sup>11</sup>
Flammability	UL94	V-0

